



October 25, 2014

To: Conexant Customer

Subject: Conexant Semiconductor Product RoHS and RoHS 2 Compliance Statement

Conexant is a strong supporter of worldwide environmental initiatives. Conexant's "Lead-Free and RoHS" semiconductor products meet the relevant materials content established by Joint Industry Guide (JIG-101) Ed. 4.1, Directive 2002/95/EC (RoHS), Directive 2011/65/EU (RoHS2), and SJ/T 11363 – 2006 (China RoHS). In addition to meeting these compliance obligations, homogeneous materials in Conexant products do not contain substances or compounds in excess of the limits indicated in the table below:

|   | Element/Compound   | Limit    |
|---|--|----------|
| <b>Directive 2002/95/EC RoHS<br/>Directive 2011/65/EU RoHS2<br/>SJ/T 11363 – 2006</b> | Lead and its Compounds   | 1000 ppm |
|   | Mercury and its Compounds  | 1000 ppm |
|   | Cadmium and its Compounds  | 100 ppm  |
|   | Hexavalent Chromium and its Compounds  | 1000 ppm |
|   | Polybrominated Biphenyls (PBB's)   | 1000 ppm |
|   | Polybrominated Diphenyl Ethers (PBDE's, including Deca-BDE)  | 1000 ppm |
| <b>PFOS Compliant (Directive 2006/122/EC)</b>   | Perfluorooctane sulfonates—PFOS<br>Exemptions: Photoresists or anti-reflective coatings for photolithography processes | 1000 ppm |
| <b>Halogen/BFR/PVC Compliant</b>  | Halogens, including Brominated Flame Retardants (other than PBB/PBDE) and PVC Compounds                                | 900 ppm  |

Conexant's lead-free leadframe-based packages are backward compatible to standard lead-based solder PCB assembly processes. This means that leadframe-based components with matte tin finish have the same form, fit, and function as standard lead-based components, and the components can be attached to a PCB using eutectic tin/lead solder paste with a standard tin/lead solder profile. Lead-free BGA components are not compatible with the standard tin/lead solder PCB assembly processes.

Conexant requires that our suppliers minimize tin-whisker formation by heat-treating all leadframe-based lead-free packages with the industry-standard post-plate bake step (150C, 1 hour). We recommend our customers follow the JEDEC reflow soldering profiles referenced in J-STD-020C.

Conexant typically identifies Pb-Free, RoHS, RoHS2 compliant products with a "Z" suffix at the end of the product dash number. In addition, IC packages are marked in compliance with requirements established in JEDEC Standard JESD97, dated May, 2004.

**NOTE:** Conexant's position is that Semiconductor products are considered components in RoHS1 and RoHS2. Therefore, CE Marking, Declaration of Conformity, and internal product control provisions stipulated in 2011/65/EU (RoHS2) Article 7 do not apply.

CONEXANT SYSTEMS, INC.

By:   
Tom Krawczyk  
Compliance Manager  
[environmental@conexant.com](mailto:environmental@conexant.com)

The signature above verifies Conexant Systems, Inc. (Conexant) has made commercially reasonable efforts to validate the accuracy of product compliance information. Substance and material composition data represented in this document has been provided to Conexant by qualified suppliers and has not been independently validated by Conexant. Conexant makes no warranties or representations whether express, implied, statutory or otherwise and Conexant expressly disclaims the implied warranties of merchantability, non-infringement and fitness for a particular purpose. Conexant assumes no liability for use of Conexant products by third parties. Information contained in this document does not amend or alter Conexant product warranty or its terms and conditions of sale.